METHOD AND PROCESS FOR EMBEDDING ELECTRICALLY CONDUCTIVE ELEMENTS IN A DIELECTRIC LAYER

ABSTRACT

A method is provided for fabricating a multilayer printed circuit board, including embedded electrically conductive elements formed as part of the fabrication of the layers of the printed circuit board. An insulating layer and a conductive layer are then pressed over the electrically conductive elements such that the electrically conductive elements protrude from the surface of the conductive layer. A mechanical process is the applied to remove these protrusions to expose the embedded electrically conductive elements. An electrically conductive undercoat may be applied over the surface of the conductive layer and a second circuit pattern is formed over the electrically conductive undercoat.

Figure 11